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Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	12
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	16-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	16-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s08sg8e2wtgr

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Revision History

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The following revision history table summarizes changes contained in this document.

Revision Number	Revision Date	Description of Changes	
0	15 Dec 2006	Initial alpha customer release version; Preliminary	
1	June 2007	Samples Draft. Updated book with the latest TPM v3 module. Includes some minor edits to the IIC module to update the Module Quick Start. Fixed the SOPT1 bits 1 and 0 to be RESERVED for both READ and WRITE. Changed all the Reset states of the Slew Rate Enable Registers (PTASE, PTBSE, and PTCSE) bits from 1 to 0 due to silicon functional change.	
2	11/2007	Market Launch. Updated the Electricals and Device Numbering scheme informa- tion.	
3	12/2007	 Fixed typos: Chapter 7 heading corrected version to v2, and Figure 16-1. title corrected to read"TPM Modules Highlighted." Table A-3. Thermal Characteristics row 1, V and M entries were transposed. V now refers to value -40 to 105°C and M now refers to value -40 to 125°C. Added row 2, parameter classification of "D" and row 4 symbol of "θ_{JA}." Table A-6. DC Characteristics, row 8 Input Hysteresis, corrected units from mV to V. 	
4	3/2008	 SPI block corrected to be version 3 of the module. Temperature Sensor values corrected to reflect the ADC 5V in Section 9.1.4 Temperature Sensor and Table A-12. ADC Characteristics. Provided Maximum juncture temperature for C, V, and M Temperature ranges. Corrected Table A-6, row 10 separated to two pins: PTB6/SDA/XTAL, RESET. Corrected block diagrams User Flash and User RAM listing typos to be SG8 and SG4 instead of SH8 and SH4. Updated the Revision History for Revision Number 1 to include the information on the Slew Rate Enable Register changes that occurred for that revision. 	
5	6/2008	 Added ICS over Temperature graph to Electricals appendix. 	

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Revision Number	Revision Date	Description of Changes
6	7/2009	 Revised NV Register 0xFFAE address to have dashes instead of 0s. Revised NVOPT register in Table 4-4 and Figure 4-6 so that Reserved is indicated with em dashes (—). Changed ICS FLL deviation to 1.5% from 2%. Table A-9, Row 1and Table A-6 footnote 10: Removed temperature reference. Table A-9, Row 9: Changed Column C to "D" and Max to "1.5%" Removed section A.14.2. Updated Mechanical drawings to point to the Freescale web. Rebuilt book to ensure proper footers and pagination. Revised all "Reserved" vector space memory locations in Table 4-1 to read, "Unused Vector Space (available for user program)."
7	7/2011	 Revised to include high-temperature (up to 150 °C) devices for 16-pin TSSOP package. In Table 2-1, added TCLK to row 20 and Alt 3 column. Updated "How to Reach Us" information.
8	1/2014	 Changes done in Chapter 3, "Modes of Operation". Updated Table 3-1 Updated PPDC column to "x" from "0" for the specification STOPE=1,ENBDM=0,LVDE and LVDSE =both bits must be 1. Changes done in Appendix A, "Electrical Characteristics" In Table A-6. DC Characteristics for column "Characteristic" moved "Reset" from parameter "P" to "C". In the Table A-6 added note 11 and 12 for parameter #18. Note 11: Device functionality is guaranteed between the LVD threshold VLVD0 and VDD Min.When VDD is below the minimum operating voltage (VDD Min), the analog parameters for the IO pins, ACMP and ADC, are not guaranteed to meet data sheet performance parameters. Note 12: In addition to LVD, it is recommended to also use the LVW feature. LVW can trigger an interrupt and be used as an indicator to warn that the VDD is dropping, so that the software can take actions accordingly before the VDD drops below VDD Min. Table A-13. Control Timing. For the parameter "Internal low power oscillator period" changed the "Min" value from "800" to "700".



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Chapter 6 Parallel Input/Output Control

6.6.2 Port B Registers

Port B is controlled by the registers listed below.

6.6.2.1 Port B Data Register (PTBD)



Figure 6-11. Port B Data Register (PTBD)

Table 6-10. PTBD Register Field Descriptions

Field	Description
7:0 PTBD[7:0]	Port B Data Register Bits — For port B pins that are inputs, reads return the logic level on the pin. For port B pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port B pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTBD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups/pull-downs disabled.

6.6.2.2 Port B Data Direction Register (PTBDD)

_	7	6	5	4	3	2	1	0
R W	PTBDD7	PTBDD6	PTBDD5	PTBDD4	PTBDD3	PTBDD2	PTBDD1	PTBDD0
Reset:	0	0	0	0	0	0	0	0

Figure 6-12. Port B Data Direction Register (PTBDD)

Table 6-11. PTBDD Register Field Descriptions

Field	Description
7:0 PTBDD[7:0]	Data Direction for Port B Bits — These read/write bits control the direction of port B pins and what is read for PTBD reads.
	 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port B bit n and PTBD reads return the contents of PTBDn.



7.4.1 Reset Sequence

Reset can be caused by a power-on-reset (POR) event, internal conditions such as the COP (computer operating properly) watchdog, or by assertion of an external active-low reset pin. When a reset event occurs, the CPU immediately stops whatever it is doing (the MCU does not wait for an instruction boundary before responding to a reset event). For a more detailed discussion about how the MCU recognizes resets and determines the source, refer to the Resets, Interrupts, and System Configuration chapter.

The reset event is considered concluded when the sequence to determine whether the reset came from an internal source is done and when the reset pin is no longer asserted. At the conclusion of a reset event, the CPU performs a 6-cycle sequence to fetch the reset vector from 0xFFFE and 0xFFFF and to fill the instruction queue in preparation for execution of the first program instruction.

7.4.2 Interrupt Sequence

When an interrupt is requested, the CPU completes the current instruction before responding to the interrupt. At this point, the program counter is pointing at the start of the next instruction, which is where the CPU should return after servicing the interrupt. The CPU responds to an interrupt by performing the same sequence of operations as for a software interrupt (SWI) instruction, except the address used for the vector fetch is determined by the highest priority interrupt that is pending when the interrupt sequence started.

The CPU sequence for an interrupt is:

- 1. Store the contents of PCL, PCH, X, A, and CCR on the stack, in that order.
- 2. Set the I bit in the CCR.
- 3. Fetch the high-order half of the interrupt vector.
- 4. Fetch the low-order half of the interrupt vector.
- 5. Delay for one free bus cycle.
- 6. Fetch three bytes of program information starting at the address indicated by the interrupt vector to fill the instruction queue in preparation for execution of the first instruction in the interrupt service routine.

After the CCR contents are pushed onto the stack, the I bit in the CCR is set to prevent other interrupts while in the interrupt service routine. Although it is possible to clear the I bit with an instruction in the interrupt service routine, this would allow nesting of interrupts (which is not recommended because it leads to programs that are difficult to debug and maintain).

For compatibility with the earlier M68HC05 MCUs, the high-order half of the H:X index register pair (H) is not saved on the stack as part of the interrupt sequence. The user must use a PSHH instruction at the beginning of the service routine to save H and then use a PULH instruction just before the RTI that ends the interrupt service routine. It is not necessary to save H if you are certain that the interrupt service routine does not use any instructions or auto-increment addressing modes that might change the value of H.

The software interrupt (SWI) instruction is like a hardware interrupt except that it is not masked by the global I bit in the CCR and it is associated with an instruction opcode within the program so it is not asynchronous to program execution.



8.1.4 Features

The ACMP has the following features:

- Full rail to rail supply operation.
- Selectable interrupt on rising edge, falling edge, or either rising or falling edges of comparator output.
- Option to compare to fixed internal bandgap reference voltage.
- Option to allow comparator output to be visible on a pin, ACMPO.
- Can operate in stop3 mode

8.1.5 Modes of Operation

This section defines the ACMP operation in wait, stop and background debug modes.

8.1.5.1 ACMP in Wait Mode

The ACMP continues to run in wait mode if enabled before executing the WAIT instruction. Therefore, the ACMP can be used to bring the MCU out of wait mode if the ACMP interrupt, ACIE is enabled. For lowest possible current consumption, the ACMP should be disabled by software if not required as an interrupt source during wait mode.

8.1.5.2 ACMP in Stop Modes

8.1.5.2.1 Stop3 Mode Operation

The ACMP continues to operate in Stop3 mode if enabled and compare operation remains active. If ACOPE is enabled, comparator output operates as in the normal operating mode and comparator output is placed onto the external pin. The MCU is brought out of stop when a compare event occurs and ACIE is enabled; ACF flag sets accordingly.

If stop is exited with a reset, the ACMP will be put into its reset state.

8.1.5.2.2 Stop2 and Stop1 Mode Operation

During either Stop2 and Stop1 mode, the ACMP module will be fully powered down. Upon wake-up from Stop2 or Stop1 mode, the ACMP module will be in the reset state.

8.1.5.3 ACMP in Active Background Mode

When the microcontroller is in active background mode, the ACMP will continue to operate normally.

8.1.6 Block Diagram

The block diagram for the Analog Comparator module is shown Figure 8-2.



Field	Description
1 ADPC17	 ADC Pin Control 17 — ADPC17 is used to control the pin associated with channel AD17. 0 AD17 pin I/O control enabled 1 AD17 pin I/O control disabled
0 ADPC16	 ADC Pin Control 16 — ADPC16 is used to control the pin associated with channel AD16. 0 AD16 pin I/O control enabled 1 AD16 pin I/O control disabled

Table 9-11. APCTL3 Register Field Descriptions (continued)

9.4 Functional Description

The ADC module is disabled during reset or when the ADCH bits are all high. The module is idle when a conversion has completed and another conversion has not been initiated. When idle, the module is in its lowest power state.

The ADC can perform an analog-to-digital conversion on any of the software selectable channels. The selected channel voltage is converted by a successive approximation algorithm into an 11-bit digital result. In 8-bit mode, the selected channel voltage is converted by a successive approximation algorithm into a 9-bit digital result.

When the conversion is completed, the result is placed in the data registers (ADCRH and ADCRL).In 10-bit mode, the result is rounded to 10 bits and placed in ADCRH and ADCRL. In 8-bit mode, the result is rounded to 8 bits and placed in ADCRL. The conversion complete flag (COCO) is then set and an interrupt is generated if the conversion complete interrupt has been enabled (AIEN = 1).

The ADC module has the capability of automatically comparing the result of a conversion with the contents of its compare registers. The compare function is enabled by setting the ACFE bit and operates in conjunction with any of the conversion modes and configurations.

9.4.1 Clock Select and Divide Control

One of four clock sources can be selected as the clock source for the ADC module. This clock source is then divided by a configurable value to generate the input clock to the converter (ADCK). The clock is selected from one of the following sources by means of the ADICLK bits.

- The bus clock, which is equal to the frequency at which software is executed. This is the default selection following reset.
- The bus clock divided by 2. For higher bus clock rates, this allows a maximum divide by 16 of the bus clock.
- ALTCLK, as defined for this MCU (See module section introduction).
- The asynchronous clock (ADACK) This clock is generated from a clock source within the ADC module. When selected as the clock source this clock remains active while the MCU is in wait or stop3 mode and allows conversions in these modes for lower noise operation.

Whichever clock is selected, its frequency must fall within the specified frequency range for ADCK. If the available clocks are too slow, the ADC will not perform according to specifications. If the available clocks



Analog-to-Digital Converter (S08ADCV1)

In cases where separate power supplies are used for analog and digital power, the ground connection between these supplies must be at the V_{SSAD} pin. This should be the only ground connection between these supplies if possible. The V_{SSAD} pin makes a good single point ground location.

9.6.1.2 Analog Reference Pins

In addition to the analog supplies, the ADC module has connections for two reference voltage inputs. The high reference is V_{REFH} , which may be shared on the same pin as V_{DDAD} on some devices. The low reference is V_{REFL} , which may be shared on the same pin as V_{SSAD} on some devices.

When available on a separate pin, V_{REFH} may be connected to the same potential as V_{DDAD} , or may be driven by an external source that is between the minimum V_{DDAD} spec and the V_{DDAD} potential (V_{REFH} must never exceed V_{DDAD}). When available on a separate pin, V_{REFL} must be connected to the same voltage potential as V_{SSAD} . Both V_{REFH} and V_{REFL} must be routed carefully for maximum noise immunity and bypass capacitors placed as near as possible to the package.

AC current in the form of current spikes required to supply charge to the capacitor array at each successive approximation step is drawn through the V_{REFH} and V_{REFL} loop. The best external component to meet this current demand is a 0.1 μ F capacitor with good high frequency characteristics. This capacitor is connected between V_{REFH} and V_{REFL} and must be placed as near as possible to the package pins. Resistance in the path is not recommended because the current will cause a voltage drop which could result in conversion errors. Inductance in this path must be minimum (parasitic only).

9.6.1.3 Analog Input Pins

The external analog inputs are typically shared with digital I/O pins on MCU devices. The pin I/O control is disabled by setting the appropriate control bit in one of the pin control registers. Conversions can be performed on inputs without the associated pin control register bit set. It is recommended that the pin control register bit always be set when using a pin as an analog input. This avoids problems with contention because the output buffer will be in its high impedance state and the pullup is disabled. Also, the input buffer draws dc current when its input is not at either V_{DD} or V_{SS} . Setting the pin control register bits for all pins used as analog inputs should be done to achieve lowest operating current.

Empirical data shows that capacitors on the analog inputs improve performance in the presence of noise or when the source impedance is high. Use of 0.01 μ F capacitors with good high-frequency characteristics is sufficient. These capacitors are not necessary in all cases, but when used they must be placed as near as possible to the package pins and be referenced to V_{SSA}.

For proper conversion, the input voltage must fall between V_{REFH} and V_{REFL} . If the input is equal to or exceeds V_{REFH} , the converter circuit converts the signal to \$3FF (full scale 10-bit representation) or \$FF (full scale 8-bit representation). If the input is equal to or less than V_{REFL} , the converter circuit converts it to \$000. Input voltages between V_{REFH} and V_{REFL} are straight-line linear conversions. There will be a brief current associated with V_{REFL} when the sampling capacitor is charging. The input is sampled for 3.5 cycles of the ADCK source when ADLSMP is low, or 23.5 cycles when ADLSMP is high.

For minimal loss of accuracy due to current injection, pins adjacent to the analog input pins should not be transitioning during conversions.



Chapter 16 Timer Pulse-Width Modulator (S08TPMV3)

16.1 Introduction

The TPM uses one input/output (I/O) pin per channel, TPMxCHn where x is the TPM number (for example, 1 or 2) and n is the channel number (for example, 0–1). The TPM shares its I/O pins with general-purpose I/O port pins (refer to the Pins and Connections chapter for more information).

All MC9S08SG8 MCUs have two TPM modules. The number of channels available depends on the pin quantity of the package, as shown in Table 16-1:

Feature	re MC9S08SG8/4		
Pin quantity	20	16	8
TPM1 channels	2	2	1 ¹
TPM2 channels	2	2	1 ¹

Table 16-1. MC9S08SG8 Features by MCU and Package

¹ The 8-pin device does not have TPM1CH1 or TPM2CH1 bonded out, but those timer channels are available to the user to use as software compares.

Figure 16-1 shows the MC9S08SG8 block diagram with the TPM modules highlighted.

16.1.1 ACMP/TPM Configuration Information

The ACMP module can be configured to connect the output of the analog comparator to TPM1 input capture channel 0 by setting ACIC in SOPT2. With ACIC set, the TPM1CH0 pin is not available externally regardless of the configuration of the TPM1 module for channel 0.

16.1.2 TPM Configuration Information

The external clock for the TPM modules, TPMCLK, is selected by setting CLKS[B:A] = 1:1 in TPMxSC, which selects the TCLK pin input. The TCLK input on PTA5 can be enabled as external clock inputs to both TPM modules and MTIM simultaneously.



16.3 Register Definition

This section consists of register descriptions in address order.

16.3.1 TPM Status and Control Register (TPMxSC)

TPMxSC contains the overflow status flag and control bits used to configure the interrupt enable, TPM configuration, clock source, and prescale factor. These controls relate to all channels within this timer module.



Figure 16-7. TPM Status and Control Register (TPMxSC)

Field	Description
7 TOF	Timer overflow flag. This read/write flag is set when the TPM counter resets to 0x0000 after reaching the modulo value programmed in the TPM counter modulo registers. Clear TOF by reading the TPM status and control register when TOF is set and then writing a logic 0 to TOF. If another TPM overflow occurs before the clearing sequence is complete, the sequence is reset so TOF would remain set after the clear sequence was completed for the earlier TOF. This is done so a TOF interrupt request cannot be lost during the clearing sequence for a previous TOF. Reset clears TOF. Writing a logic 1 to TOF has no effect. 0 TPM counter has not reached modulo value or overflow 1 TPM counter has overflowed
6 TOIE	Timer overflow interrupt enable. This read/write bit enables TPM overflow interrupts. If TOIE is set, an interrupt is generated when TOF equals one. Reset clears TOIE. 0 TOF interrupts inhibited (use for software polling) 1 TOF interrupts enabled
5 CPWMS	 Center-aligned PWM select. When present, this read/write bit selects CPWM operating mode. By default, the TPM operates in up-counting mode for input capture, output compare, and edge-aligned PWM functions. Setting CPWMS reconfigures the TPM to operate in up/down counting mode for CPWM functions. Reset clears CPWMS. 0 All channels operate as input capture, output compare, or edge-aligned PWM mode as selected by the MSnB:MSnA control bits in each channel's status and control register. 1 All channels operate in center-aligned PWM mode.
4–3 CLKS[B:A]	Clock source selects. As shown in Table 16-6, this 2-bit field is used to disable the TPM system or select one of three clock sources to drive the counter prescaler. The fixed system clock source is only meaningful in systems with a PLL-based system clock. When there is no PLL, the fixed-system clock source is the same as the bus rate clock. The external source is synchronized to the bus clock by TPM module, and the fixed system clock source (when a PLL is present) is synchronized to the bus clock by an on-chip synchronization circuit. When a PLL is present but not enabled, the fixed-system clock source is the same as the bus-rate clock.
2–0 PS[2:0]	Prescale factor select. This 3-bit field selects one of 8 division factors for the TPM clock input as shown in Table 16-7. This prescaler is located after any clock source synchronization or clock source selection so it affects the clock source selected to drive the TPM system. The new prescale factor will affect the clock source on the next system clock cycle after the new value is updated into the register bits.

Table 16-5. TPMxSC Field Descriptions



Timer/PWM Module (S08TPMV3)

Input capture, output compare, and edge-aligned PWM functions do not make sense when the counter is operating in up/down counting mode so this implies that all active channels within a TPM must be used in CPWM mode when CPWMS=1.

The TPM may be used in an 8-bit MCU. The settings in the timer channel registers are buffered to ensure coherent 16-bit updates and to avoid unexpected PWM pulse widths. Writes to any of the registers TPMxMODH, TPMxMODL, TPMxCnVH, and TPMxCnVL, actually write to buffer registers.

In center-aligned PWM mode, the TPMxCnVH:L registers are updated with the value of their write buffer according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), the registers are updated after the both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter, the update is made when the TPM counter changes from 0xFFFE to 0xFFFF.

When TPMxCNTH:TPMxCNTL=TPMxMODH:TPMxMODL, the TPM can optionally generate a TOF interrupt (at the end of this count).

Writing to TPMxSC cancels any values written to TPMxMODH and/or TPMxMODL and resets the coherency mechanism for the modulo registers. Writing to TPMxCnSC cancels any values written to the channel value registers and resets the coherency mechanism for TPMxCnVH:TPMxCnVL.

16.5 Reset Overview

16.5.1 General

The TPM is reset whenever any MCU reset occurs.

16.5.2 Description of Reset Operation

Reset clears the TPMxSC register which disables clocks to the TPM and disables timer overflow interrupts (TOIE=0). CPWMS, MSnB, MSnA, ELSnB, and ELSnA are all cleared which configures all TPM channels for input-capture operation with the associated pins disconnected from I/O pin logic (so all MCU pins related to the TPM revert to general purpose I/O pins).

16.6 Interrupts

16.6.1 General

The TPM generates an optional interrupt for the main counter overflow and an interrupt for each channel. The meaning of channel interrupts depends on each channel's mode of operation. If the channel is configured for input capture, the interrupt flag is set each time the selected input capture edge is recognized. If the channel is configured for output compare or PWM modes, the interrupt flag is set each time the main timer counter matches the value in the 16-bit channel value register.



Timer/PWM Module (S08TPMV3)

16.6.2.1.2 Center-Aligned PWM Case

When CPWMS=1, TOF gets set when the timer counter changes direction from up-counting to down-counting at the end of the terminal count (the value in the modulo register). In this case the TOF corresponds to the end of a PWM period.

16.6.2.2 Channel Event Interrupt Description

The meaning of channel interrupts depends on the channel's current mode (input-capture, output-compare, edge-aligned PWM, or center-aligned PWM).

16.6.2.2.1 Input Capture Events

When a channel is configured as an input capture channel, the ELSnB:ELSnA control bits select no edge (off), rising edges, falling edges or any edge as the edge which triggers an input capture event. When the selected edge is detected, the interrupt flag is set. The flag is cleared by the two-step sequence described in Section 16.6.2, "Description of Interrupt Operation."

16.6.2.2.2 Output Compare Events

When a channel is configured as an output compare channel, the interrupt flag is set each time the main timer counter matches the 16-bit value in the channel value register. The flag is cleared by the two-step sequence described Section 16.6.2, "Description of Interrupt Operation."

16.6.2.2.3 PWM End-of-Duty-Cycle Events

For channels configured for PWM operation there are two possibilities. When the channel is configured for edge-aligned PWM, the channel flag gets set when the timer counter matches the channel value register which marks the end of the active duty cycle period. When the channel is configured for center-aligned PWM, the timer count matches the channel value register twice during each PWM cycle. In this CPWM case, the channel flag is set at the start and at the end of the active duty cycle period which are the times when the timer counter matches the channel value register. The flag is cleared by the two-step sequence described Section 16.6.2, "Description of Interrupt Operation."



the host must perform ((8 - CNT) - 1) dummy reads of the FIFO to advance it to the first significant entry in the FIFO.

In most trigger modes, the information stored in the FIFO consists of 16-bit change-of-flow addresses. In these cases, read DBGFH then DBGFL to get one coherent word of information out of the FIFO. Reading DBGFL (the low-order byte of the FIFO data port) causes the FIFO to shift so the next word of information is available at the FIFO data port. In the event-only trigger modes (see Section 17.3.5, "Trigger Modes"), 8-bit data information is stored into the FIFO. In these cases, the high-order half of the FIFO (DBGFH) is not used and data is read out of the FIFO by simply reading DBGFL. Each time DBGFL is read, the FIFO is shifted so the next data value is available through the FIFO data port at DBGFL.

In trigger modes where the FIFO is storing change-of-flow addresses, there is a delay between CPU addresses and the input side of the FIFO. Because of this delay, if the trigger event itself is a change-of-flow address or a change-of-flow address appears during the next two bus cycles after a trigger event starts the FIFO, it will not be saved into the FIFO. In the case of an end-trace, if the trigger event is a change-of-flow, it will be saved as the last change-of-flow entry for that debug run.

The FIFO can also be used to generate a profile of executed instruction addresses when the debugger is not armed. When ARM = 0, reading DBGFL causes the address of the most-recently fetched opcode to be saved in the FIFO. To use the profiling feature, a host debugger would read addresses out of the FIFO by reading DBGFH then DBGFL at regular periodic intervals. The first eight values would be discarded because they correspond to the eight DBGFL reads needed to initially fill the FIFO. Additional periodic reads of DBGFH and DBGFL return delayed information about executed instructions so the host debugger can develop a profile of executed instruction addresses.

17.3.3 Change-of-Flow Information

To minimize the amount of information stored in the FIFO, only information related to instructions that cause a change to the normal sequential execution of instructions is stored. With knowledge of the source and object code program stored in the target system, an external debugger system can reconstruct the path of execution through many instructions from the change-of-flow information stored in the FIFO.

For conditional branch instructions where the branch is taken (branch condition was true), the source address is stored (the address of the conditional branch opcode). Because BRA and BRN instructions are not conditional, these events do not cause change-of-flow information to be stored in the FIFO.

Indirect JMP and JSR instructions use the current contents of the H:X index register pair to determine the destination address, so the debug system stores the run-time destination address for any indirect JMP or JSR. For interrupts, RTI, or RTS, the destination address is stored in the FIFO as change-of-flow information.

17.3.4 Tag vs. Force Breakpoints and Triggers

Tagging is a term that refers to identifying an instruction opcode as it is fetched into the instruction queue, but not taking any other action until and unless that instruction is actually executed by the CPU. This distinction is important because any change-of-flow from a jump, branch, subroutine call, or interrupt causes some instructions that have been fetched into the instruction queue to be thrown away without being executed.



A force-type breakpoint waits for the current instruction to finish and then acts upon the breakpoint request. The usual action in response to a breakpoint is to go to active background mode rather than continuing to the next instruction in the user application program.

The tag vs. force terminology is used in two contexts within the debug module. The first context refers to breakpoint requests from the debug module to the CPU. The second refers to match signals from the comparators to the debugger control logic. When a tag-type break request is sent to the CPU, a signal is entered into the instruction queue along with the opcode so that if/when this opcode ever executes, the CPU will effectively replace the tagged opcode with a BGND opcode so the CPU goes to active background mode rather than executing the tagged instruction. When the TRGSEL control bit in the DBGT register is set to select tag-type operation, the output from comparator A or B is qualified by a block of logic in the debug module that tracks opcodes and only produces a trigger to the debugger if the opcode at the compare address is actually executed. There is separate opcode tracking logic for each comparator so more than one compare event can be tracked through the instruction queue at a time.

17.3.5 Trigger Modes

The trigger mode controls the overall behavior of a debug run. The 4-bit TRG field in the DBGT register selects one of nine trigger modes. When TRGSEL = 1 in the DBGT register, the output of the comparator must propagate through an opcode tracking circuit before triggering FIFO actions. The BEGIN bit in DBGT chooses whether the FIFO begins storing data when the qualified trigger is detected (begin trace), or the FIFO stores data in a circular fashion from the time it is armed until the qualified trigger is detected (end trigger).

A debug run is started by writing a 1 to the ARM bit in the DBGC register, which sets the ARMF flag and clears the AF and BF flags and the CNT bits in DBGS. A begin-trace debug run ends when the FIFO gets full. An end-trace run ends when the selected trigger event occurs. Any debug run can be stopped manually by writing a 0 to ARM or DBGEN in DBGC.

In all trigger modes except event-only modes, the FIFO stores change-of-flow addresses. In event-only trigger modes, the FIFO stores data in the low-order eight bits of the FIFO.

The BEGIN control bit is ignored in event-only trigger modes and all such debug runs are begin type traces. When TRGSEL = 1 to select opcode fetch triggers, it is not necessary to use R/W in comparisons because opcode tags would only apply to opcode fetches that are always read cycles. It would also be unusual to specify TRGSEL = 1 while using a full mode trigger because the opcode value is normally known at a particular address.

The following trigger mode descriptions only state the primary comparator conditions that lead to a trigger. Either comparator can usually be further qualified with R/W by setting RWAEN (RWBEN) and the corresponding RWA (RWB) value to be matched against R/W. The signal from the comparator with optional R/W qualification is used to request a CPU breakpoint if BRKEN = 1 and TAG determines whether the CPU request will be a tag request or a force request.



17.4.1.1 BDC Status and Control Register (BDCSCR)

This register can be read or written by serial BDC commands (READ_STATUS and WRITE_CONTROL) but is not accessible to user programs because it is not located in the normal memory map of the MCU.



= Unimplemented or Reserved

Figure 17-5. BDC Status and Control Register (BDCSCR)

Table 17-2. BDCSCR Register Field Descriptions

Field	Description						
7 ENBDM	 Enable BDM (Permit Active Background Mode) — Typically, this bit is written to 1 by the debug host shortly after the beginning of a debug session or whenever the debug host resets the target and remains 1 until a normal reset clears it. 0 BDM cannot be made active (non-intrusive commands still allowed) 1 BDM can be made active to allow active background mode commands 						
6 BDMACT	 Background Mode Active Status — This is a read-only status bit. 0 BDM not active (user application program running) 1 BDM active and waiting for serial commands 						
5 BKPTEN	 BDC Breakpoint Enable — If this bit is clear, the BDC breakpoint is disabled and the FTS (force tag select) control bit and BDCBKPT match register are ignored. 0 BDC breakpoint disabled 1 BDC breakpoint enabled 						
4 FTS	 Force/Tag Select — When FTS = 1, a breakpoint is requested whenever the CPU address bus matches the BDCBKPT match register. When FTS = 0, a match between the CPU address bus and the BDCBKPT register causes the fetched opcode to be tagged. If this tagged opcode ever reaches the end of the instruction queue, the CPU enters active background mode rather than executing the tagged opcode. 0 Tag opcode at breakpoint address and enter active background mode if CPU attempts to execute that instruction 1 Breakpoint match forces active background mode at next instruction boundary (address need not be an opcode) 						
3 CLKSW	Select Source for BDC Communications Clock — CLKSW defaults to 0, which selects the alternate BDC clock source. 0 Alternate BDC clock source 1 MCU bus clock						



17.4.3.9 Debug Status Register (DBGS)

This is a read-only status register.



Figure 17-9. Debug Status Register (DBGS)

Table 17-6. DBGS Register Field Descriptions
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Field	Description						
7 AF	 Trigger Match A Flag — AF is cleared at the start of a debug run and indicates whether a trigger match A condition was met since arming. 0 Comparator A has not matched 1 Comparator A match 						
6 BF	 Trigger Match B Flag — BF is cleared at the start of a debug run and indicates whether a trigger match B condition was met since arming. 0 Comparator B has not matched 1 Comparator B match 						
5 ARMF	 Arm Flag — While DBGEN = 1, this status bit is a read-only image of ARM in DBGC. This bit is set by writing 1 to the ARM control bit in DBGC (while DBGEN = 1) and is automatically cleared at the end of a debug run. A debug run is completed when the FIFO is full (begin trace) or when a trigger event is detected (end trace). A debug run can also be ended manually by writing 0 to ARM or DBGEN in DBGC. 0 Debugger not armed 1 Debugger armed 						
3:0 CNT[3:0]	FIFO Valid Count — These bits are cleared at the start of a debug run and indicate the number of words of valid data in the FIFO at the end of a debug run. The value in CNT does not decrement as data is read out of the FIFO. The external debug host is responsible for keeping track of the count as information is read out of the FIFO. 0000 Number of valid words in FIFO = No valid data 0001 Number of valid words in FIFO = 1 0010 Number of valid words in FIFO = 2 0011 Number of valid words in FIFO = 3 0100 Number of valid words in FIFO = 4 0101 Number of valid words in FIFO = 5 0110 Number of valid words in FIFO = 5 0110 Number of valid words in FIFO = 7 1000 Number of valid words in FIFO = 7 1000 Number of valid words in FIFO = 8						



Appendix A Electrical Characteristics

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (for instance, either V_{SS} or V_{DD}) or the programmable pull-up resistor associated with the pin is enabled.

			Unit	Temp Rated ¹		
Rating	Symbol	Value		Standard	AEC Grade 0	
Supply voltage	V _{DD}	-0.3 to +5.8	V	х	х	
Maximum current into V _{DD}	I _{DD}	120	mA	х	х	
Digital input voltage	V _{In}	–0.3 to V _{DD} + 0.3	V	х	х	
Instantaneous maximum current Single pin limit (applies to all port pins) ^{2, 3, 4}	Ι _D	± 25	mA	х	х	
Storage temperature range	T _{stg}	-55 to 150	°C	х	х	

Table A-2. Absolute Maximum Ratings

¹ Electrical characteristics only apply to the temperature rated devices marked with x.

² Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive (V_{DD}) and negative (V_{SS}) clamp voltages, then use the larger of the two resistance values.

 $^3\,$ All functional non-supply pins are internally clamped to V_{SS} and V_{DD}

⁴ Power supply must maintain regulation within operating V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current (V_{In} > V_{DD}) is greater than I_{DD}, the injection current may flow out of V_{DD} and could result in external power supply going out of regulation. Ensure external V_{DD} load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power. Examples are: if no system clock is present, or if the clock rate is very low (which would reduce overall power consumption).



A.13 FLASH Specifications

This section provides details about program/erase times and program-erase endurance for the FLASH memory.

Program and erase operations do not require any special power sources other than the normal V_{DD} supply. For more detailed information about program/erase operations, see the Memory section.

						Temp Rated ¹			
Nu m	С	Characteristic	Symbol	Min	Typical	Max	Unit	Stand ard	AEC Grade 0
1	_	Supply voltage for program/erase	V _{prog/erase}	2.7		5.5	V	х	х
2	_	Supply voltage for read operation	V _{Read}	2.7		5.5	V	х	х
3	—	Internal FCLK frequency ²	f _{FCLK}	150		200	kHz	х	х
4	-	Internal FCLK period (1/f _{FCLK})	t _{Fcyc}	5		6.67	μS	х	х
5	_	Byte program time (random location) ³	t _{prog}	9			t _{Fcyc}	x	x
6	_	Byte program time (burst mode) ²	t _{Burst}	4			t _{Fcyc}	x	x
7	-	Page erase time ²	t _{Page}	4000			t _{Fcyc}	х	х
8	—	Mass erase time ²	t _{Mass}	20,000			t _{Fcyc}	х	х
9	с	Program/erase endurance ⁴ T_L to $T_H = -40^{\circ}C$ to +125°C T_L to $T_H = -40^{\circ}C$ to +150°C $T = 25^{\circ}C$	n _{FLPE}	10,000 10,000 10,000	 100,000		cycles	x 	
10	С	Data retention ⁵	t _{D_ret}	15	100	—	years	x	x

Table A-16. FLASH Character

¹ Electrical characteristics only apply to the temperature rated devices marked with x.

² The frequency of this clock is controlled by a software setting.

³ These values are hardware state machine controlled. User code does not need to count cycles. This information supplied for calculating approximate time to program and erase.

⁴ Typical endurance for FLASH is based on the intrinsic bit cell performance. For additional information on how Freescale defines typical endurance, please refer to Engineering Bulletin EB619/D, Typical Endurance for Nonvolatile Memory.

⁵ Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25°C using the Arrhenius equation. For additional information on how Freescale defines typical data retention, please refer to Engineering Bulletin EB618/D, Typical Data Retention for Nonvolatile Memory.



Appendix B Ordering Information and Mechanical Drawings

B.2 Mechanical Drawings

The following pages are mechanical specifications for MC9S08SG8 package options. See Table B-2 for the document number for each package type.

Pin Count	Туре	Designator	Document No.
20	TSSOP	TJ	98ASH70169A
16	TSSOP	TG	98ASH70247A
8	NB SOIC	SC	98ASB42564B

Table B-2. Package Information